



IN THE UNITED STATES PATENT &
TRADEMARK OFFICE

IN RE Application of: HARTWELL, ET AL

USSN: 10/066,213

FILED: 02/01/2002

REQUEST FOR CORRECTION OF FILING RECEIPT

Honorable Assistant Commissioner for Patents
Washington, D.C. 20231

Please correct the attached filing receipt as follows:

PLEASE NOTE THAT THE FOLLOWING IS INCORRECT:

THE TITLE

THE CORRECT INFORMATION READS:

METHODS FOR DICING WAFER STACKS TO PROVIDE ACCESS TO INTERIOR
STRUCTURES

I attach a copy of THE INCORRECT FILING RECEIPT, THE COVER OF THE
SPECIFICATION and THE DECLARATION.

Respectfully Submitted,

Anthony J. Baca
REG. NO. 33,472

HEWLETT-PACKARD COMPANY
IP ADMINISTRATION, M/S 35
LEGAL DEPARTMENT
3404 EAST HARMONY ROAD
FORT COLLINS, CO 80527-2400

DOCKET NO. 10006165-1

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Page 1 of 2
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COMMISSIONER FOR PATENTS
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO.	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/066,213 ✓	02/01/2002 ✓	2812	740	10006165-1 ✓	8	20	3

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CONFIRMATION NO. 5663 ✓

HEWLETT-PACKARD COMPANY
Intellectual Property Administration
P.O. Box 272400
Fort Collins, CO 80527-2400

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FILING RECEIPT



OC000000007558622

Date Mailed: 02/28/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Peter G. Hartwell, Sunnyvale, CA; ✓
David Horsley, Berkeley, CA; ✓
Storrs T. Hoen, Brisbane, CA; ✓
Jonah A. Harley, Palo Alto, CA; ✓

Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted 02/28/2002

Projected Publication Date: 08/07/2003

Non-Publication Request: No

Early Publication Request: No

Title

Method for dicing wafer stacks to provide access to interior structures ✓

Preliminary Class

438

Should be plural - "Methods"

**LICENSE FOR FOREIGN FILING UNDER
Title 35, United States Code, Section 184
Title 37, Code of Federal Regulations, 5.11 & 5.15**

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I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" services under 37 C.F.R. 1.10 on the date indicated above and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Typed Name of Person Mailing Paper or Fee: Chris Griffin

Signature: Chris Griffin

PATENT APPLICATION
DOCKET NO. 10006165-1

Methods For Dicing Wafer Stacks To Provide
Access To Interior Structures

INVENTOR(S):

Peter G. Hartwell

David Horsley

Storrs T. Hoen

Jonah A. Harley

**DECLARATION AND POWER OF ATTORNEY
FOR PATENT APPLICATION**

AT KEY DOCKET NO. 10006185-1

As a below named inventor, I hereby declare that:

My residence/post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Methods For Dicing Wafer Stacks To Provide Access To Interior Structures

the specification of which is attached hereto unless the following box is checked:

() was filed on _____ as US Application No. or PCT International Application
Number _____ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understood the contents of the above-identified specification, including the claims, as amended by any amendment(s) referred to above. I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR 1.56.

Foreign Application(s) and/or Claim of Foreign Priority

I hereby claim foreign priority benefits under Title 35, United States Code Section 119 of any foreign application(s) for patent or inventor(s) certificate listed below and have also identified below any foreign application for patent or inventor(s) certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NUMBER	DATE FILED	PRIORITY CLAIMED UNDER 35 U.S.C. 119
			YES: _____ NO: _____
			YES: _____ NO: _____

Provisional Application

I hereby claim the benefit under Title 35, United States Code Section 119(e) of any United States provisional application(s) listed below:

APPLICATION NUMBER	FILING DATE

U. S. Priority Claim

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION NUMBER	FILING DATE	STATUS (patented/pending/abandoned)

POWER OF ATTORNEY:

As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

Customer Number **022879**

Place Customer
Number Bar Code
Label here

Send Correspondence to:
HEWLETT-PACKARD COMPANY
Intellectual Property Administration
P.O. Box 272400
Fort Collins, Colorado 80527-2400

Direct Telephone Calls To:

Anthony J Baca
(208) 398-3597

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Inventor: Peter G. Hartwell

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Residence: 459 Bryan Ave., Sunnyvale, CA 94086

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Inventor's Signature: 

Date: 11/16/2001

DECLARATION AND POWER OF ATTORNEY
FOR PATENT APPLICATION (continued)

ATTORNEY DOCKET NO. 10006165 -1

Full Name of # 2 joint inventor: David Horsley Citizenship: US
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Full Name of # 4 joint inventor: Jonah A. Harley Citizenship: US
Residence: 1735 Woodland Avenue #19, Palo Alto, California 94303
Post Office Address: Same as residence
Inventor's signature: Jonah A. Harley Date: 11-14-01

Full Name of # 5 joint inventor: _____ Citizenship: _____
Residence: _____
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Inventor's signature: _____ Date: _____

Full Name of # 6 joint inventor: _____ Citizenship: _____
Residence: _____
Post Office Address: _____
Inventor's signature: _____ Date: _____

Full Name of # 7 joint inventor: _____ Citizenship: _____
Residence: _____
Post Office Address: _____
Inventor's signature: _____ Date: _____

Full Name of # 8 joint inventor: _____ Citizenship: _____
Residence: _____
Post Office Address: _____
Inventor's signature: _____ Date: _____